

Materials Declaration

Package	LFCSP
Body Size	4 X 4 X 0.85
LeadCount	24
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84	1.18 E-02	280402
Mutiaromatic Resin	16	2.25 E-03	53414
Subtotal		1.40 E-02	333816

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.21 E-02	524497
Fe	2.35	5.44 E-04	12926
Zn	0.12	2.70 E-05	642
P	0.03	7.00 E-06	166
Subtotal		2.27 E-02	538231

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	5.04 E-04	11979

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	7.27 E-04	17274

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	4.17 E-04	9908

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	2.97 E-03	70570

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70	5.37 E-04	12760
Resin	21	1.61 E-04	3826
Metal Oxide	3	2.30 E-05	547
Amine	3	2.30 E-05	547
Gamma Butyrolactone	3	2.30 E-05	547
Subtotal		7.67 E-04	18225

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/M/S
PBDE	Not Detected	EPA Method 3540C/3550C. GC/M/S

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	3	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/M/S
PBDE	Not Detected	EPA Method 3540C/3550C. GC/M/S

Package Totals

Weight (g)	PPM
4.21 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability for any inaccuracy of such information.



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Materials Declaration

Package	LFCSP
Body Size	4 X 4 X 0.85
LeadCount	24
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84	1.18 E-02	280003
Mutiaromatic Resin	16	2.25 E-03	53338
Subtotal		1.40 E-02	333341

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.21 E-02	523751
Fe	2.35	5.44 E-04	12908
Zn	0.12	2.70 E-05	641
P	0.03	7.00 E-06	166
Subtotal		2.27 E-02	537465

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	5.04 E-04	11958

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	6.69 E-04	15873
Pb	15	1.18 E-04	2800
Subtotal		7.87 E-04	18673

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	4.17 E-04	9894

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	2.97 E-03	70469

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70	5.37 E-04	12741
Resin	21	1.61 E-04	3820
Metal Oxide	3	2.30 E-05	546
Amine	3	2.30 E-05	546
Gamma Butyrolactone	3	2.30 E-05	546
Subtotal		7.67 E-04	18199

Package Totals

Weight (g)	PPM
4.21 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/M/S
PBDE	Not Detected	EPA Method 3540C/3550C. GC/M/S

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
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PBB	Not Detected	EPA Method 3540C/3550C. GC/M/S
PBDE	Not Detected	EPA Method 3540C/3550C. GC/M/S

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